



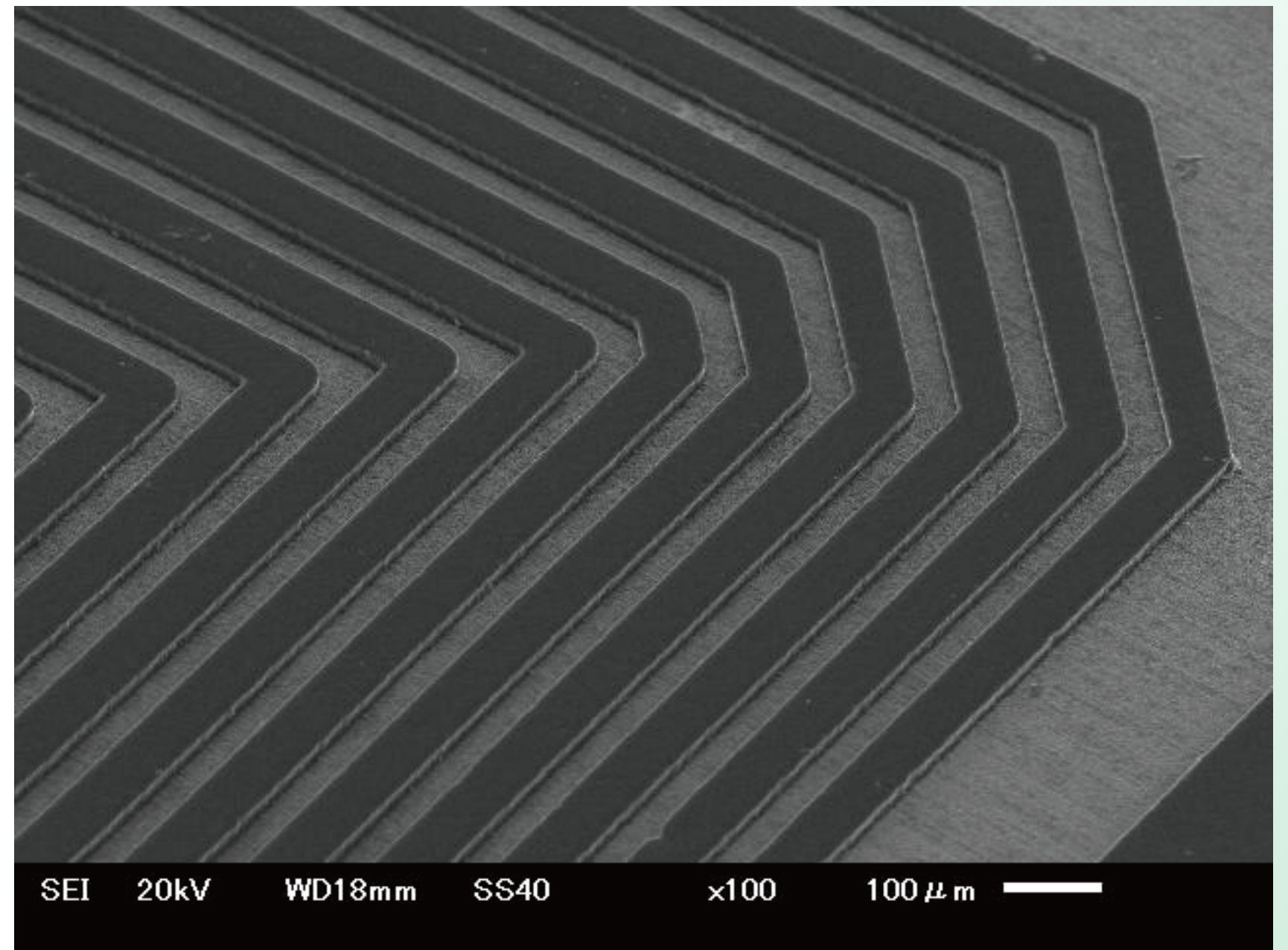
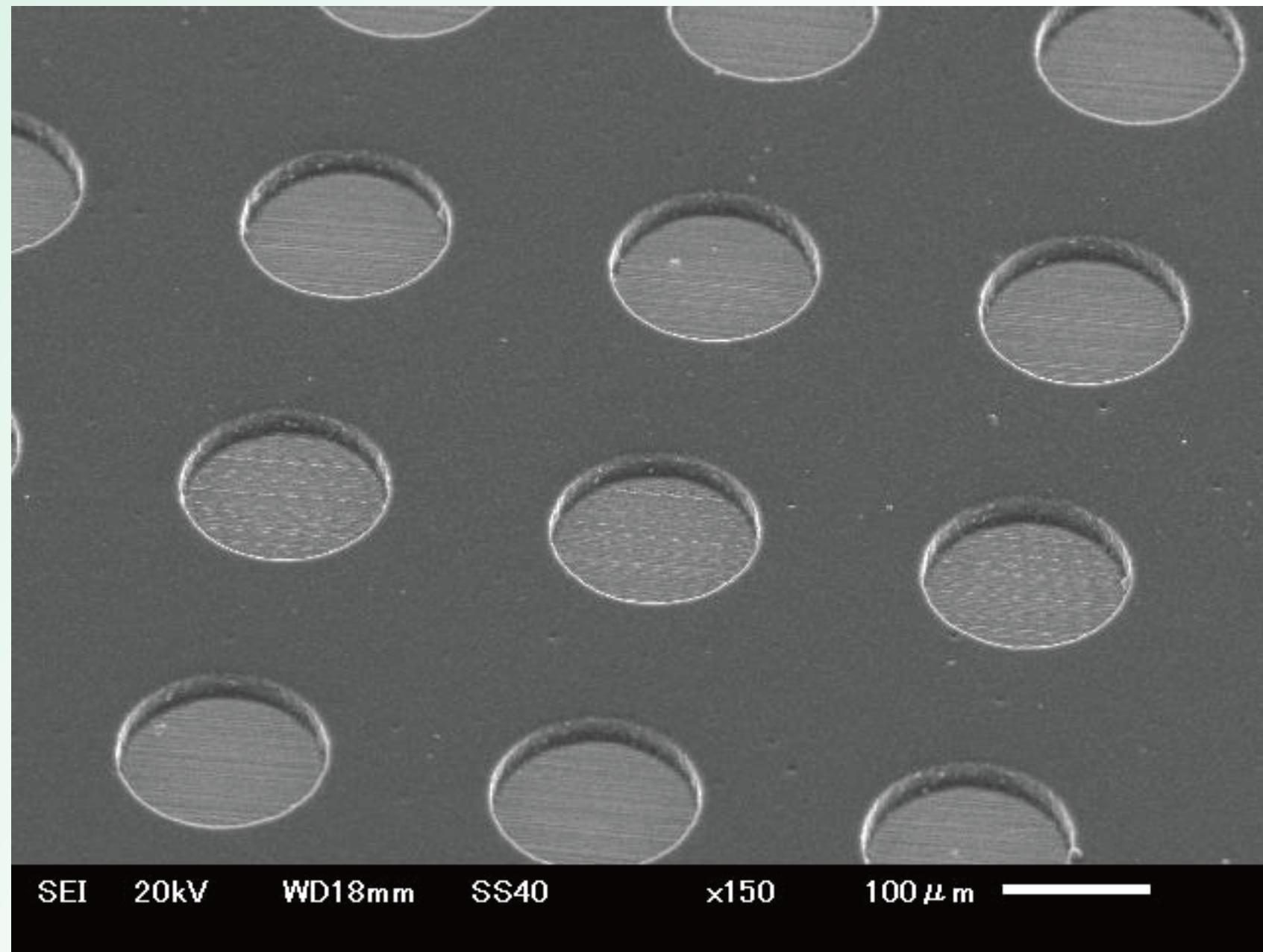
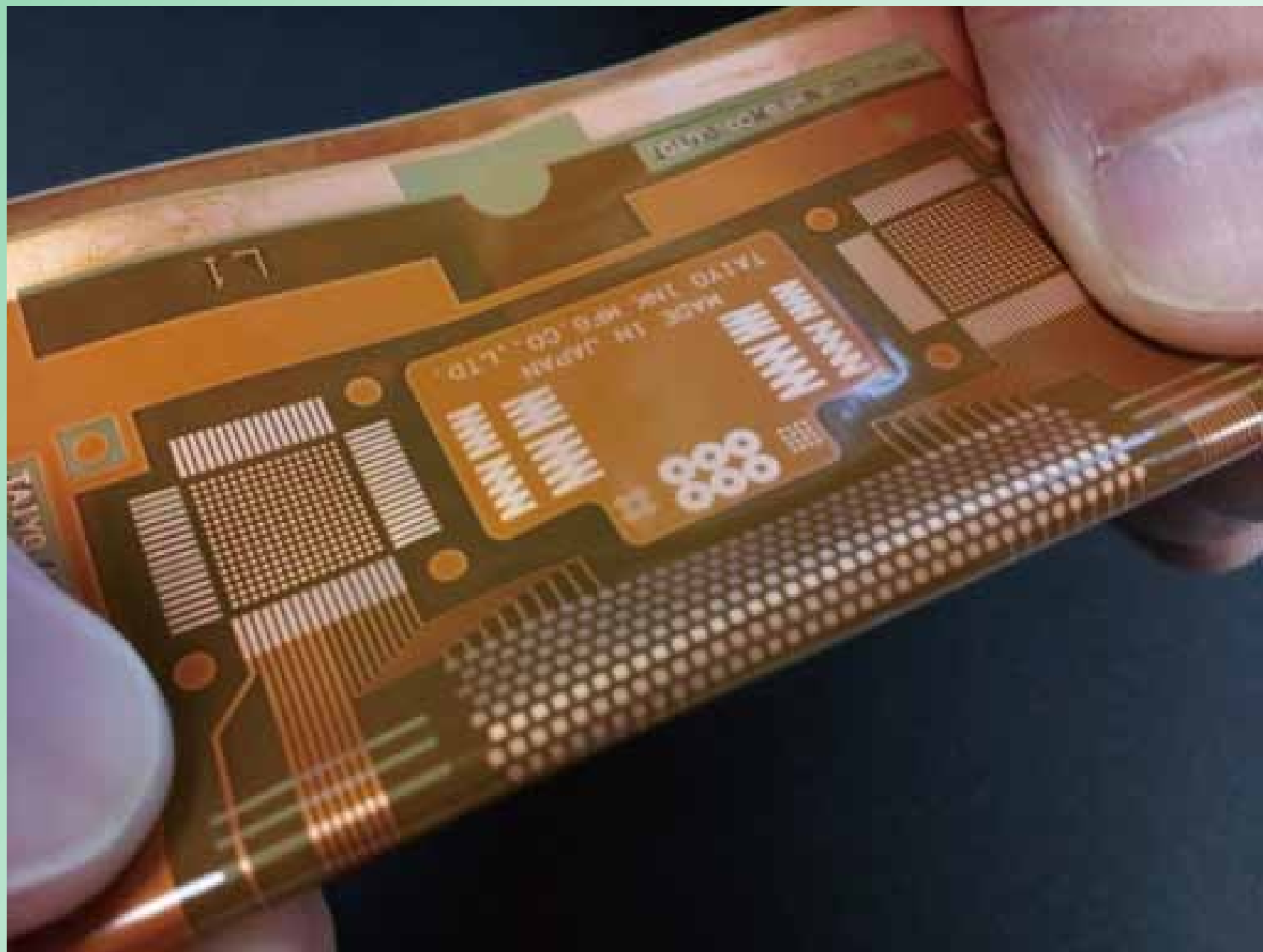
感光性カバーレイフィルム

Photo Imageable Cover Lay Film

特徴 Features



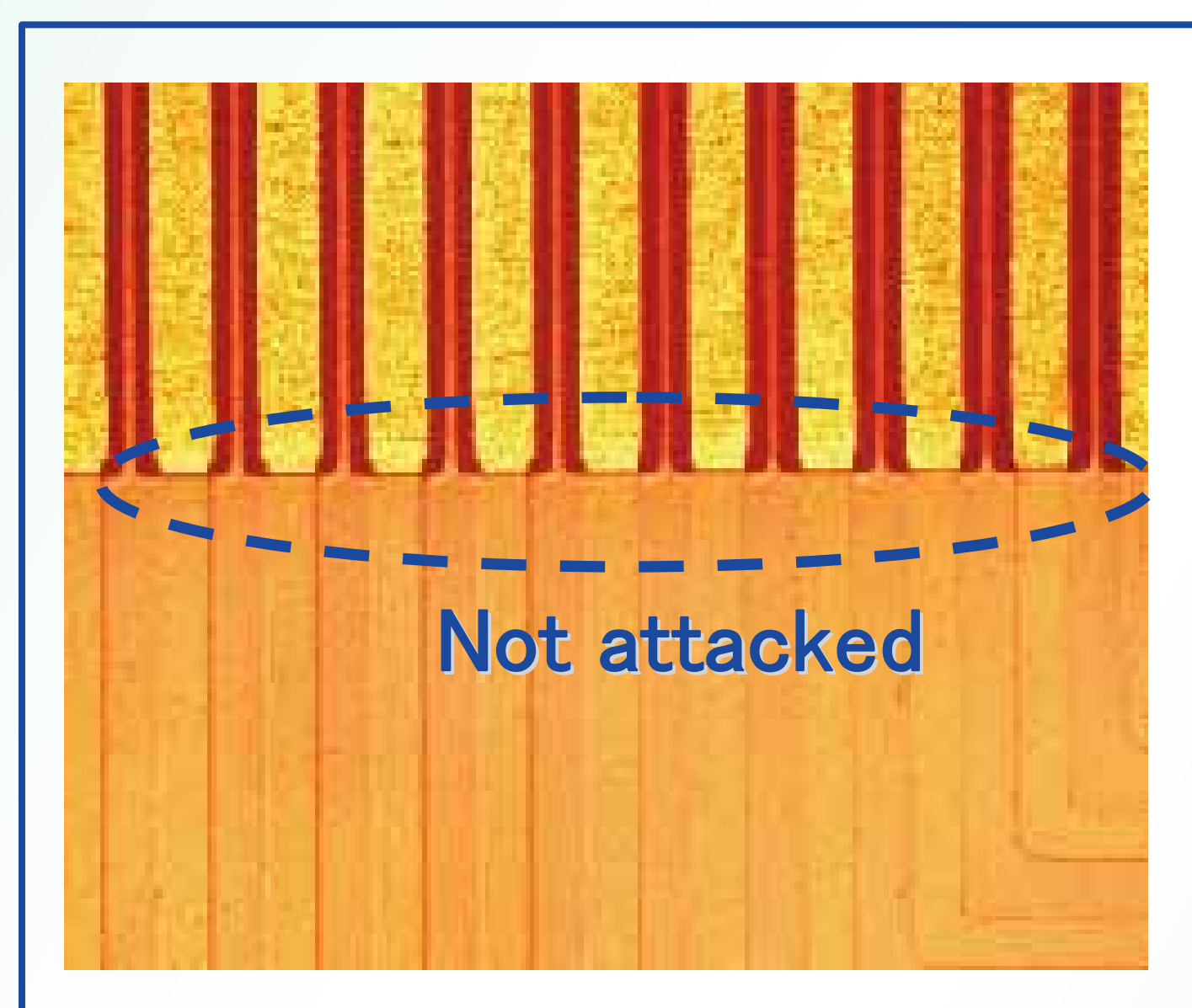
- 高解像性と高屈曲性の両立を実現した感光性ポリイミドフィルム
Photo imageable polyimide film with coexistence of high resolution and high bendability
- 現行のプリント配線板製造ラインへの適用を実現
Applicable to current PWB photolithography process
- 優れた耐熱性と絶縁信頼性と難燃性（VTM-0 相当）を実現
Excellent heat resistance, insulation reliability and flame resistance (VTM-0 equivalent)



特性 Properties

Item	Condition	Result
Pencil hardness	JIS 5600	4H
Acid resistance	10 vol% H ₂ SO ₄ aq. 25 deg.C×20 min	Pass
Alkaline resistance	10 wt% NaOHaq. 25 deg.C×20 min	Pass
Heat resistance	Solder floating 288 deg.C×10 sec	Pass
Au plating resistance	ENIG Ni:4 um Au:0.1um	Pass
Tg	TMA	160 deg.C
Bendability	180deg. folding	above 20 times

★ENIG resistance [Ni:4.0um Au:0.1um]



★Solder heat resistance [288deg.C×10sec×2 times]

